한국전기전자재료학회 2007년도 하계학술대회 논문집

입자침전법을 이용한 광도전체 필름의 X선 반응 특성에 관한 연구

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Abstract: Flat-panel direct conversion detectors used in compound substance of semiconductor are being studied for digital x-ray imaging. Recently, such detectors are deposited by physical vapor deposition(PVD) generally. But, most of materials (HgI2, PbI2, TlBr, PbO) deposited by PVD have shown difficult fabrication and instability for large area x-ray imaging. Consequently, in this paper, we propose applicable potentialities for screen printing method that is coated on a substrate easily.

It is compared to electrical properties among semiconductors such as HgI₂, PbI₂, PbO, HgBrI, InI, and TlPbI₃ under investigation for direct conversion detectors. Each film detector consists of an ~25 to 35 µm thick layer of semiconductor and was coated onto the substrate. Substrates of 2cm×2cm have been used to evaluate performance of semiconductor radiation detectors. Dark current, sensitivity and physics properties were measured. Leakage current of HgI₂ as low as 9pA/mm² at the operation bias voltage of ~1V/µm was observed. Such a value is not better than PVD process, but it is easy to be fabricated in high quality for large area x-ray Imaging. Our future efforts will concentrate on optimization of growth of film thickness that is coated onto a-Si TFT array.

Key Words: X-ray Detector, Digital Radiography, Photoconductor Film, Particle in Binder Method